

# ESH120N80R1V

## ev™ Automotive Grade Silicon Carbide Power MOSFET

1200V, 30A, 80mΩ

### Features

- High switching speed with a low gate charge
- Very fast diode with low reverse recovery
- Robust Avalanche Capability
- 100% Avalanche Tested
- Easy to Parallel and Simple to Drive
- Pb-free, Halogen Free, and RoHS Compliant
- Qualified to AEC-Q101

### Benefits

- Higher System Efficiency
- Higher Frequency Applicability
- Increased Power Density
- Reduced Cooling Requirements

### Applications

- On-board Charger/PFC
- DC-DC Converter
- Auxiliary Inverter

BV <sub>DSS, Tc=25°C</sub>	I <sub>D, Tc=25°C</sub>	R <sub>DS(on), typ.</sub>	Q <sub>g, typ.</sub>
1200V	30A	80mΩ	50nC



### Ordering Information

Part Number	Package	Shipping	Quantity
ESH120N80R1V	TO-247	Tube	30 units

### Absolute Maximum Ratings (T<sub>J</sub>=25°C, unless otherwise specified)

Symbol	Parameter	Value	Unit	
V <sub>DSS</sub>	Drain to Source Voltage	1200	V	
V <sub>GS</sub>	Gate to Source Voltage (DC)	-10/+22		
V <sub>GSop</sub>	Recommended Operation Value	-5/+18		
I <sub>D</sub>	Continuous Drain Current	T <sub>C</sub> =25°C	30	A
		T <sub>C</sub> =100°C	21	
I <sub>DM</sub>	Pulsed Drain Current (Note1)	T <sub>C</sub> =25°C	80	
P <sub>D</sub>	Power Dissipation	T <sub>C</sub> =25°C	150	W
		T <sub>C</sub> =100°C	75	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 175	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering, 1/8" from Case for 10 Seconds	260	°C	

Note1: Limited by maximum junction temperature.

## ■ Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	1.00	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	40	

## ■ Electrical Characteristics ( $T_C=25^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	1200			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=1200V, V_{GS}=0V$		1	100	$\mu A$
		$V_{DS}=1200V, V_{GS}=0V, T_J=175^\circ\text{C}$		5		
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=+22V, V_{DS}=0V$			+100	nA
		$V_{GS}=-10V, V_{DS}=0V$			-100	

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=5.0mA$	2.0	3.0	4.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS}=18V, I_D=15A$		80	104	m $\Omega$
		$V_{GS}=18V, I_D=15A, T_J=175^\circ\text{C}$		128		
$g_{fs}$	Transconductance	$V_{DS}=20V, I_D=15A$		11.4		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS}=800V, V_{GS}=0V, f=1MHz$		885		$\mu F$
$C_{oss}$	Output Capacitance			65		
$C_{rss}$	Reverse Capacitance			5		
$E_{oss}$	Stored Energy in Output Capacitance			26		$\mu J$
$Q_{g(tot)}$	Total Gate Charge	$V_{DS}=800V, I_D=15A,$ $V_{GS}=-5V/18V,$ Inductive load		50		nC
$Q_{gs}$	Gate to Source Charge			13		
$Q_{gd}$	Gate to Drain "Miller" Charge			17		
$R_G$	Internal Gate Resistance	$f=1MHz$		4.0		$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=800V, I_D=15A,$ $V_{GS}=-5V/18V, R_G=2\Omega,$ Inductive load		14		ns
$t_r$	Turn-On Rise Time			21		
$t_{d(off)}$	Turn-Off Delay Time			24		
$t_f$	Turn-Off Fall Time			9		
$E_{on}$	Turn-On Switching Energy			250		$\mu J$
$E_{off}$	Turn-Off Switching Energy			42		
$E_{tot}$	Total Switching Energy			292		

■ **Reverse Diode Characteristics** ( $T_C=25^{\circ}\text{C}$ , unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Diode Forward Current	$V_{GS}=-5V$			30	A
$I_{SM}$	Pulsed Diode Forward Current	$V_{GS}=-5V$			80	
$V_{SD}$	Diode Forward Voltage	$V_{GS}=-5V, I_{SD}=15A$		4.1		V
		$V_{GS}=-5V, I_{SD}=15A, T_J=175^{\circ}\text{C}$		3.6		
$t_{rr}$	Reverse Recovery Time	$V_{DD}=800V, I_{SD}=15A, V_{GS}=-5V,$ $dI_S/dt=1000A/\mu s$		32		ns
$Q_{rr}$	Reverse Recovery Charge			112		nC
$E_{rec}$	Reverse Recovery Energy			6.5		$\mu\text{J}$
$I_{rrm}$	Peak Reverse Recovery Current			8.0		A

■ **Typical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Figure 1. On-Region Characteristics  $T_J=-40^\circ\text{C}$

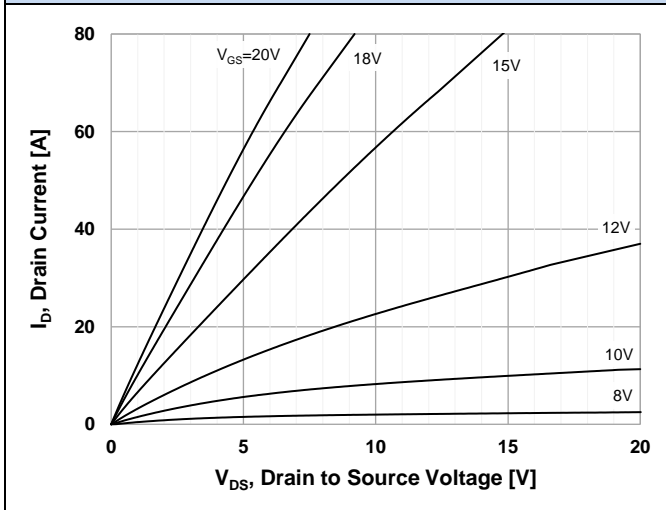


Figure 2. On-Region Characteristics  $T_J=25^\circ\text{C}$

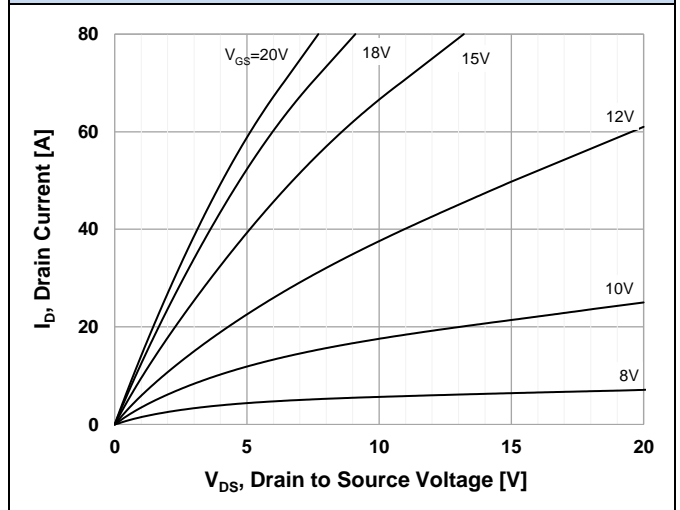


Figure 3. On-Region Characteristics  $T_J=125^\circ\text{C}$

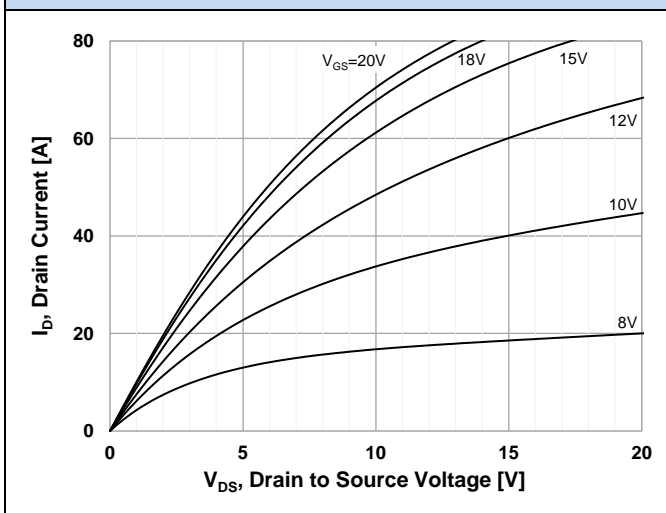


Figure 4. Normalized On-Region Characteristics vs. Temperature

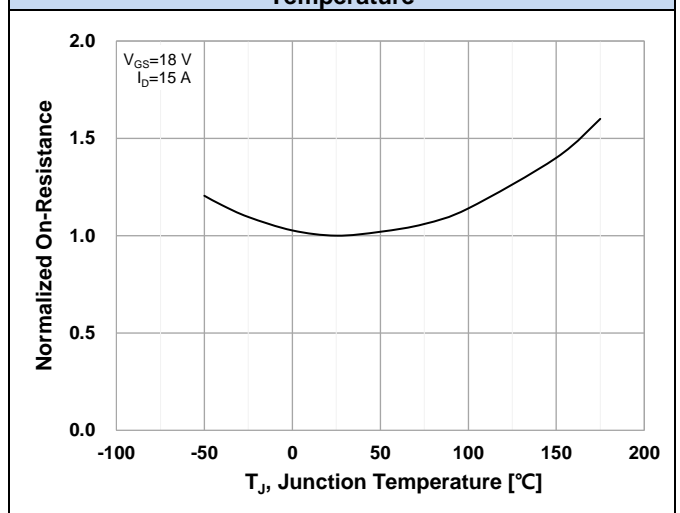


Figure 5. Transfer Characteristics

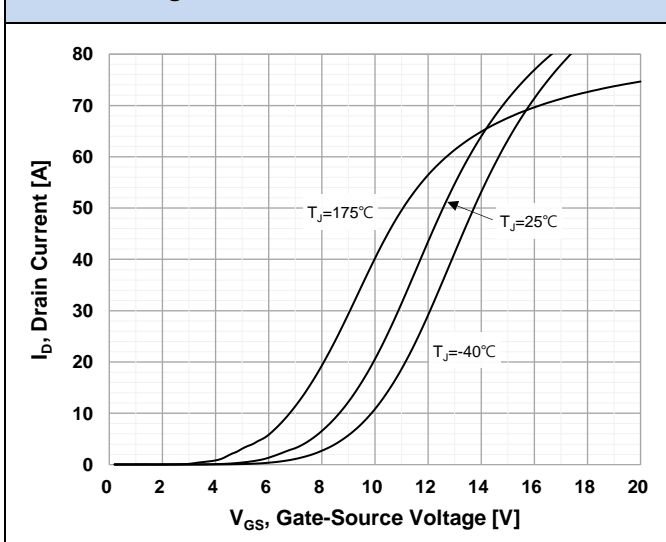
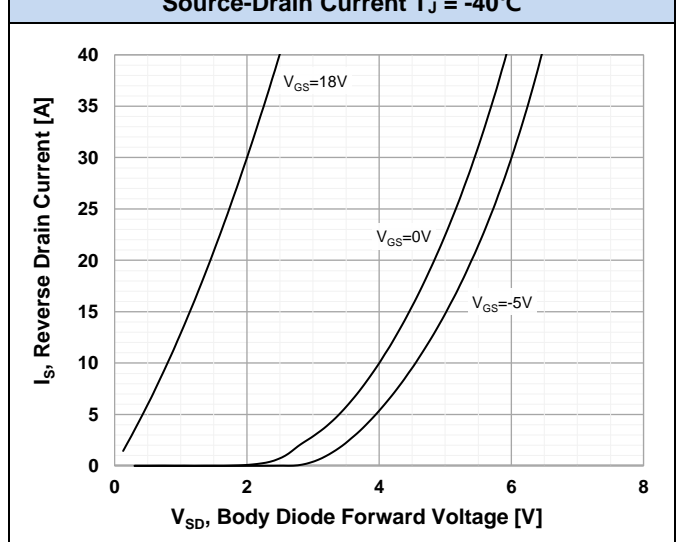


Figure 6. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J = -40^\circ\text{C}$



■ Typical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Figure 7. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J=25^\circ\text{C}$

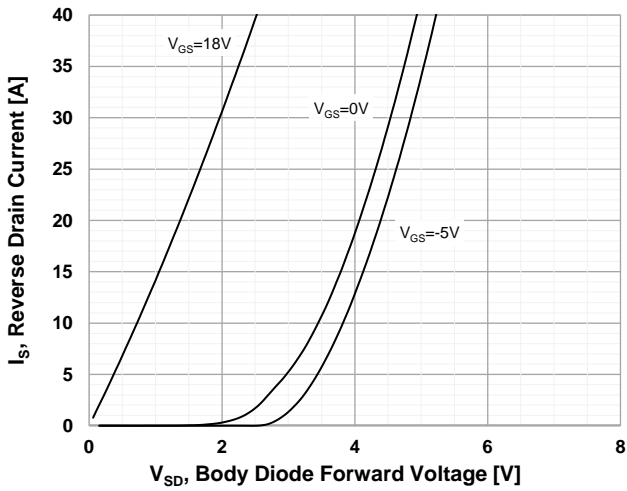


Figure 8. Diode Forward Voltage Characteristics vs. Source-Drain Current  $T_J=175^\circ\text{C}$

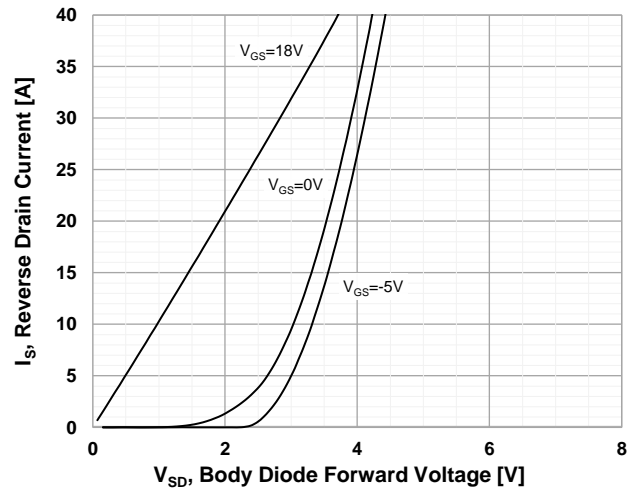


Figure 9. Threshold Voltage vs. Temperature

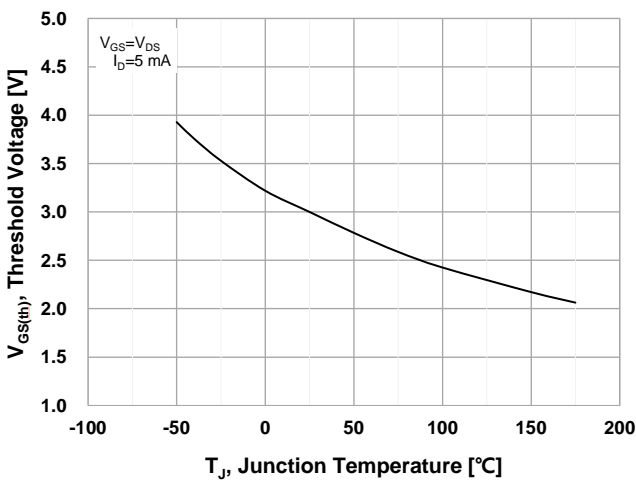


Figure 10. Gate Charge Characteristics

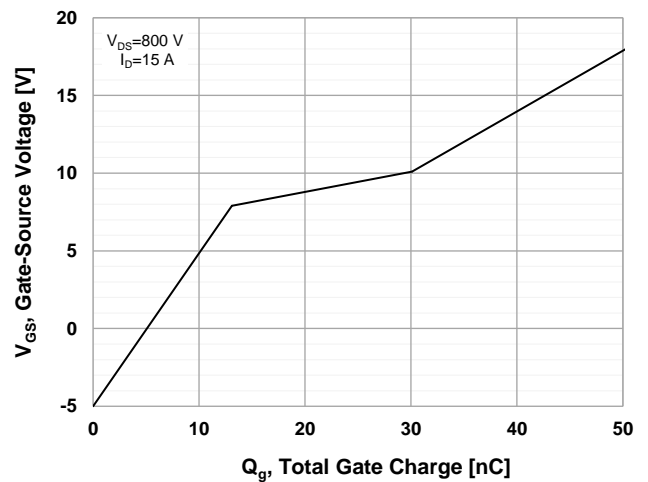


Figure 11. Stored Energy in Output Capacitance

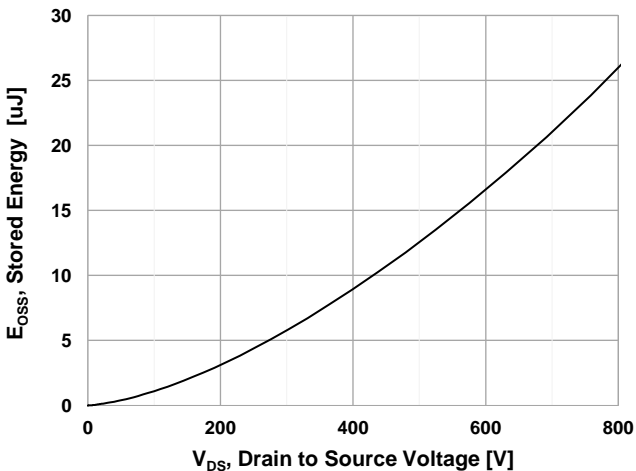
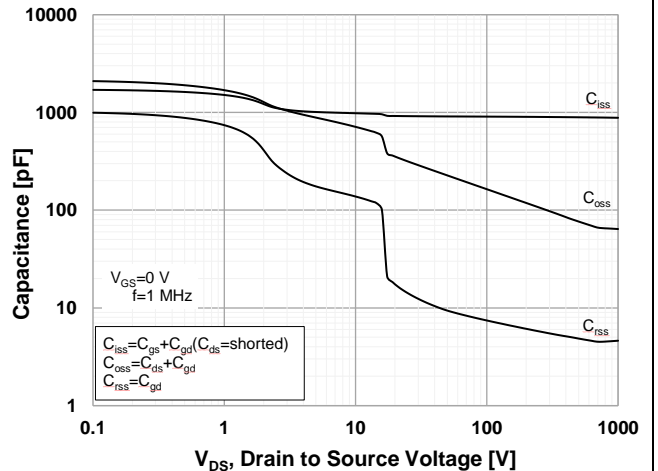
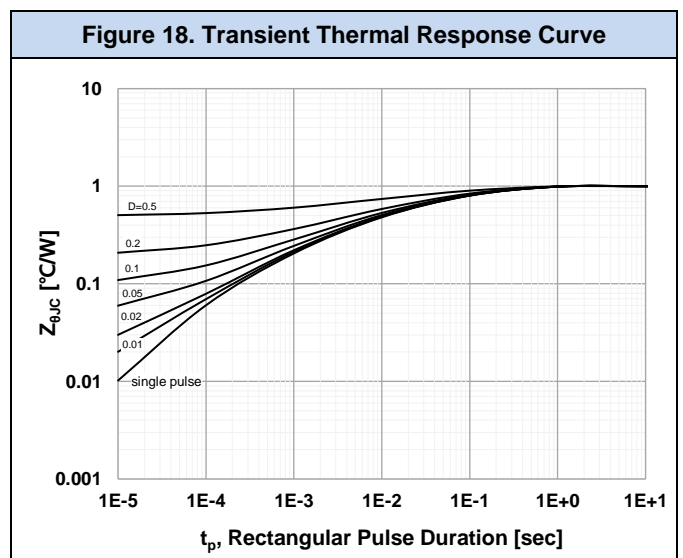
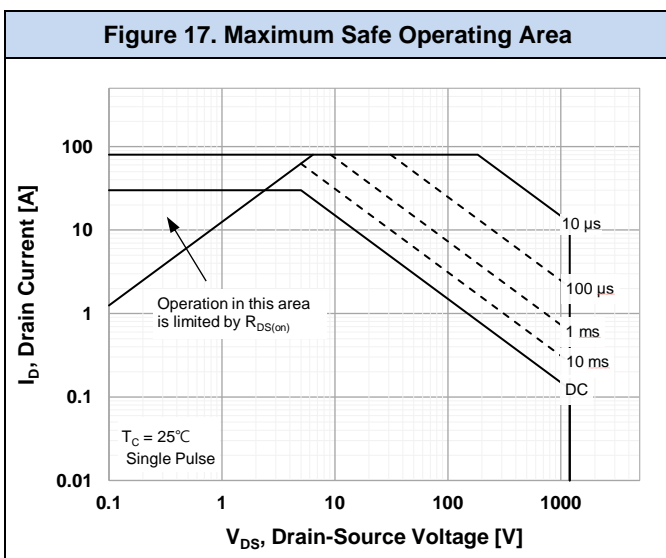
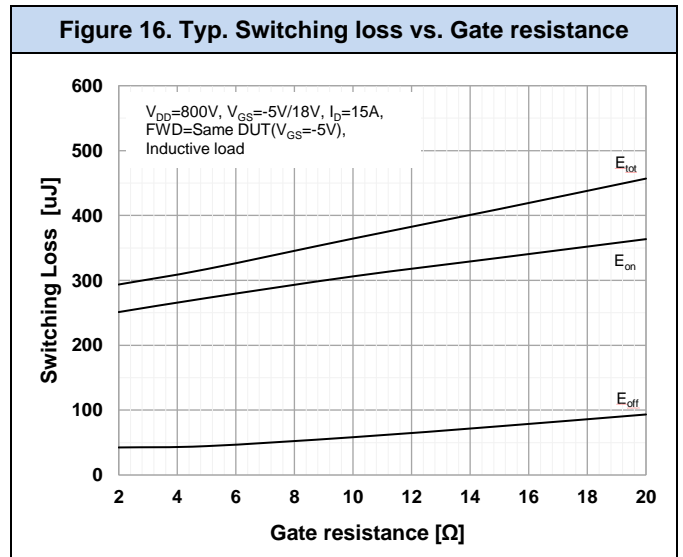
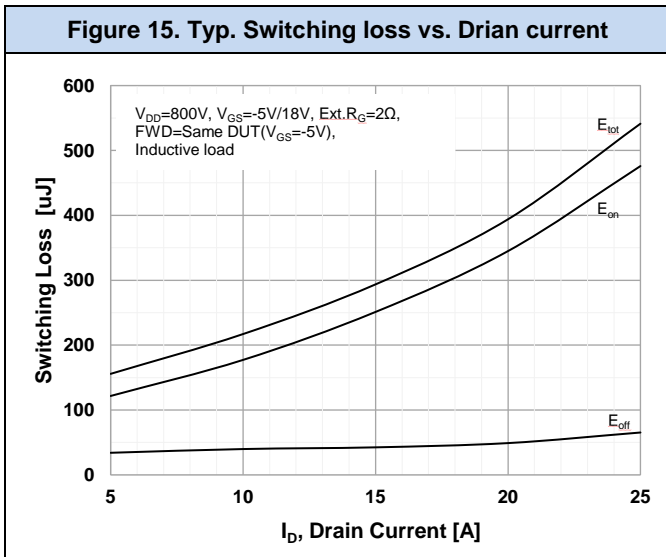
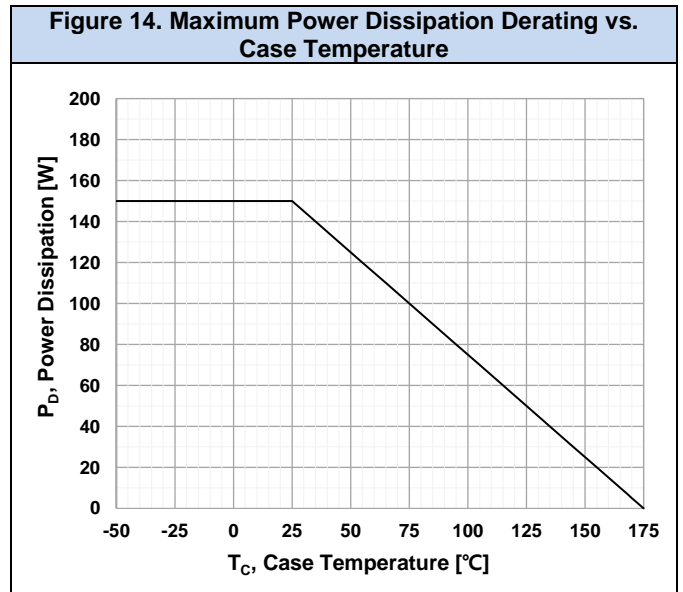
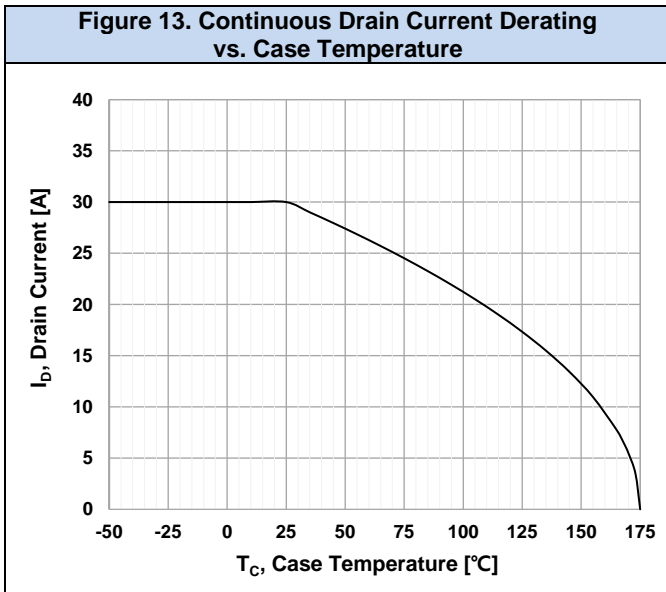


Figure 12. Capacitance Characteristics



■ Typical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)



■ Test Conditions

Figure 19. Inductive Load Switching Test Circuit and Waveforms

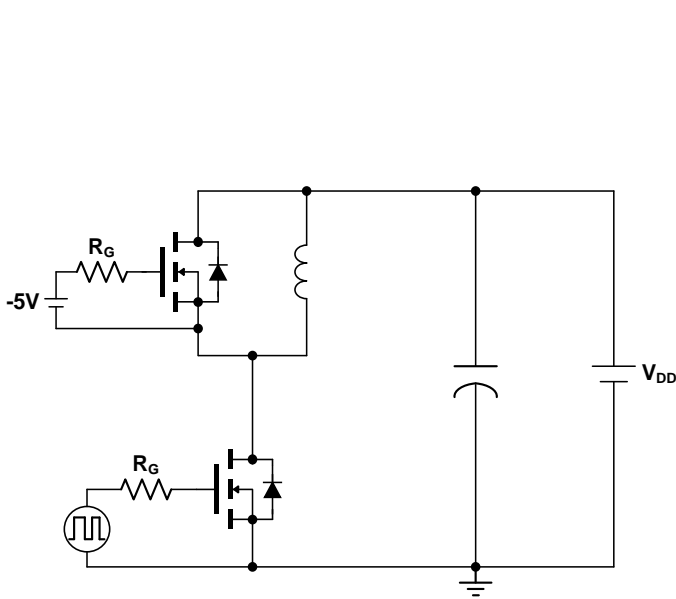


Figure A. Inductive Switching Test Circuit

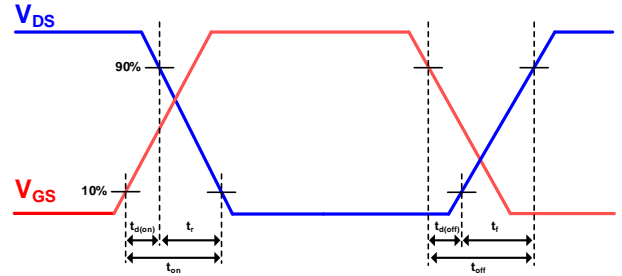


Figure B. Inductive Switching Waveforms

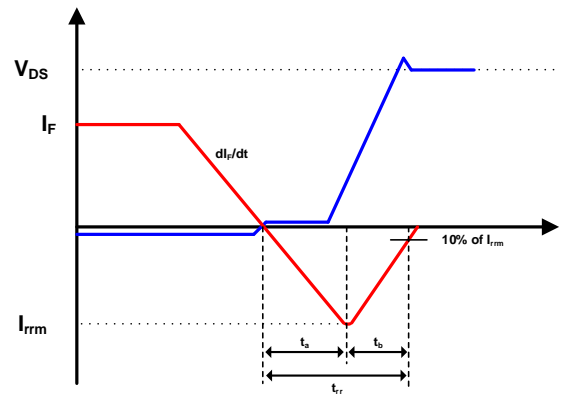
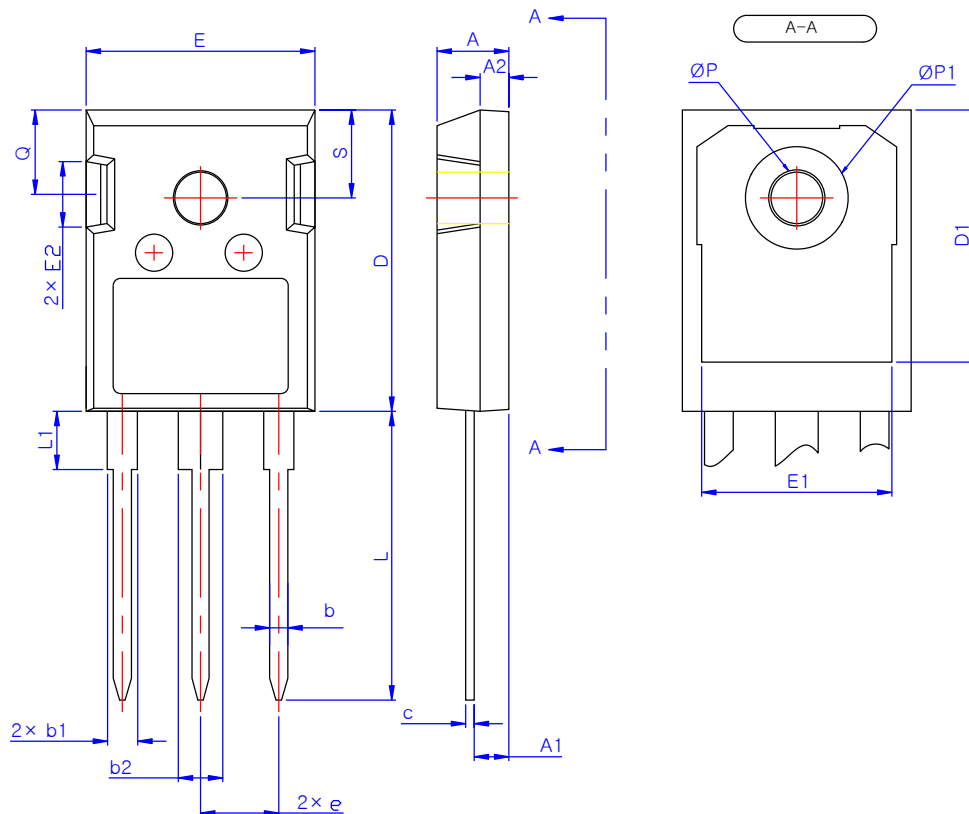


Figure C. Diode Switching Waveforms

# Package Outlines TO-247



SYMBOL	MIN	MAX
A	4.80	5.20
A1	2.29	2.54
A2	1.90	2.10
b	1.10	1.30
b1	1.91	2.20
b2	2.92	3.20
c	0.50	0.70
D	20.80	21.34
D1	17.43	17.83
E	15.75	16.13
E1	13.06	13.46
E2	4.32	4.83
e	5.45 BSC	
L	19.85	20.25
L1	-	4.49
ØP	3.55	3.65
ØP1	7.08	7.28
Q	5.59	6.19
S	6.15 BSC	

\*Dimensions in millimeters



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